

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A method of assembling a semiconductor device and a lead frame, the lead frame having a plurality of lead fingers in strip form, each lead finger of the plurality of lead fingers having a bonding end, the plurality of lead fingers forming an opening for a semiconductor device, the lead frame having no die paddle for supporting the semiconductor device thereon, comprising:

[providing a lead frame having a plurality of lead fingers in strip form having a pair of side rails connecting each lead frame to another lead frame in the strip, each lead finger of the plurality of lead fingers having a bonding end, the plurality of lead fingers forming an opening at least a size of an attachment surface of a semiconductor device, the lead frame having no die paddle for supporting the semiconductor device thereon;]

[forming a segment of tape having a shape to fit over at least the bonding end of each lead finger of the plurality of lead fingers of the lead frame forming the opening, the segment of tape extending between the plurality of lead fingers across the opening, the segment of tape having a thermosetting adhesive located in a portion thereof;]

adhesively attaching the segment of tape to portions of the lead frame [at least the bonding end of each lead finger of the plurality of lead fingers of the lead frame], the segment of tape extending across the opening having a thermosetting adhesive located thereon forming [the segment of tape providing] an attachment location for the semiconductor device [through use of the thermosetting adhesive]; and

[adhesively] attaching the semiconductor device to at least a portion of the segment of tape at the attachment location for the semiconductor device using the thermosetting adhesive located on a portion of the segment of tape, the semiconductor device having a portion thereof located within the opening formed by the plurality of lead fingers of the lead frame.

2. (Original) The method of claim 1, further including:
forming at least one aperture in the segment of tape.

3. (Original) The method of claim 1, further including:
forming a plurality of apertures in the segment of tape.

4. (Original) The method of claim 3, wherein the plurality of apertures substantially
forms a grid-like pattern of apertures.

5. (Previously Presented) The method of claim 2, wherein the semiconductor device
is attached to the segment of tape such that at least a portion of an outer periphery of the
semiconductor device is adjacent to a portion of a periphery of the at least one aperture.

6. (Previously Presented) The method of claim 3, wherein the semiconductor device
is attached to the segment of tape such that at least a portion of an outer periphery of the
attachment surface of the semiconductor device is positioned within at least one aperture of the
plurality of apertures.

7. (Original) The method of claim 1, further including:
wire bonding contacts of the semiconductor device to the bonding ends of the plurality of lead
fingers.

8. (Original) The method of claim 1, further including:
packaging the semiconductor device in an encapsulating material to form a packaged
semiconductor device.

9. (Original) The method of claim 8, further comprising:
forming the segment of tape to fit within the encapsulating material.

10. (Currently Amended) A method of assembling a semiconductor device and a lead frame, said lead frame having a plurality of lead fingers, each lead finger of the plurality of lead fingers having an end forming an opening between the ends of the plurality of lead fingers of the lead frame having a size of at least the attachment surface of the semiconductor device,

comprising:

[providing a lead frame having a plurality of lead fingers in strip form having a pair of side rails connecting each lead frame to another in the strip, each lead finger of the plurality of lead fingers having an end forming an opening between the ends of the plurality of lead fingers of the lead frame having a size of one of at least a size of an attachment surface of a semiconductor device and greater than the attachment surface of the semiconductor device;]

[forming at least two tape segments shaped to fit over a portion of the ends of the plurality of lead fingers of the lead frame, the at least two tape segments extending across the opening having a size of one of at least the size of the attachment surface of the semiconductor device and greater than the attachment surface of the semiconductor device; and]

[adhesively] attaching at least two tape segments to portions of the lead frame [the portion of the ends of the plurality of lead fingers], the at least two tape segments being spaced to define at least one opening between the at least two tape segments providing an attachment location for the semiconductor device therein, said at least two tape segments shaped for extending across the opening forming the attachment surface of the semiconductor device.

11. (Previously Presented) The method of claim 10, further including forming a plurality of apertures in at least one tape segment of the at least two tape segments.

12. (Original) The method of claim 11, wherein the plurality of apertures substantially forms a grid-like pattern of apertures.

13. (Previously Presented) The method of claim 11, further including:
attaching the semiconductor device to the at least one tape segment of the at least two tape segments having at least a portion of an outer periphery of the semiconductor device adjacent to a periphery of at least one aperture of the plurality of apertures.

14. (Previously Presented) The method of claim 13, wherein the semiconductor device is attached to the at least one tape segment such that at least a portion of the outer periphery of the semiconductor device is positioned within the at least one aperture of the plurality of apertures.

15. (Original) The method of claim 13, further including:
wire bonding contacts of the semiconductor device to the ends of the plurality of lead fingers.

16. (Original) The method of claim 10, further including:
packaging the semiconductor device in an encapsulating material to form a packaged semiconductor integrated circuit device.

17. (Previously Presented) The method of claim 16, further comprising forming the at least two tape segments to fit within the encapsulating material.

18. (Previously Presented) The method of claim 10, wherein the at least two tape segments comprises three or more tape segments.

19. (Previously Presented) The method of claim 10, further including forming at least one aperture in at least one tape segment of the at least two tape segments.

20. (Previously Presented) The method of claim 10, wherein the adhesively attaching the at least two tape segments to the portion of the ends of the plurality of lead fingers comprises spacing the at least two tape segments to define at least two openings between the at least two tape segments.